Since 1980

3D VISION INSPECTION



3D VISION INSPECTION - 3000



3D VISION INSPECTION - 3000R
**Tape & Reel off-loader Equipped



High Productivity

• 100,000 UPH (Based on Dry Run)



Most Advanced Vision Inspection

•Capable to Handle for BGA, QFN, LEADED Camera Module, TMV & WLP Packages



Excellent 3D Vision Inspection Technology

 PMP (Phase Measurement Profilometry Technology)



Package Side Inspection (Optional)

 Enable to Inspect Package Cutting Surface (QFN, QLP, MLP, MLF, LFCSP, Camera Module)



3D VISION INSPECTION

Enhanced Machine Features

■ Latest Innovation in Vision Inspection Technology

- True 3D Inspection in PMP Technology
- 3-Dimentional Mapping Function
- Best Inspection Accuracy by Actual Volume Scanning on Objects (Not by Brightness Control)
- Solution for Warpage & Coplanarity Inspection
- Applicable for Both Top / Bottom Side for 3D Inspection
- Package Side Module (Optional)

■ High Accuracy & Precise Handling

- Package Handling Accuracy: ± 20µm
- Minimum Package Size: 3x3 or less (Both QFN & BGA in Tray)
- Minimization for Machine Vibration

■ Machine Flexibility & Quick Change-Over

- Various Off-loading Options (Tray, Tube or Tape & Reel)
- Multi-reject Sorting Function
- Capability to Handle All Types of Semiconductor Packages
- Extremely Easy & Quick Change-over: Max. 10 minutes
- Universal Picker Applied

■ Advanced Operation System (HMI)

- Automatic Image Save & Statistic Process Control (SPC)
- PC Based Easy-to-use & Real-time Graphical User Interface
- Detail Maintenance Guide on LCD Touch Screen Monitor

■ Productivity and Capability

Productivity	UPH	100,000 (Based on QFN 3x3, 18x30 Tray, 540 Units)	Performance	MTBA	2 hours
Capability	PKG Handling Acc.	± 20 μm		MTBF	168 hours
	Min. PKG size	3mm x 3mm			
	Max. PKG size	50mm x 50mm		~~~~	3 minutes
	Types of Package	Leaded, Leadless, Camera Module, CSP, TMV, WLP		MTTA	
	Vision FOV	70mm x 52mm		MTTR	30 minutes









